IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

pplicant:

Brian Taggart et al.

2825

Serial No.:

10/807,830

Examiner:

Art Unit:

Calvin Lee

Filed:

March 24, 2004

Docket:

ITL.1119US

P18791

§ § §

For:

Lower Profile Flexible Substrate

Package for Electronic Components

Assignee:

Intel Corporation

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

REPLY TO PAPER NO. 2

Sir:

In response to the office action mailed January 4, 2005, please amend the abovereferenced patent application as follows:

Date of Deposit: March 7, 2005

I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Cynthia L. Hayden